



Product Change Notification - JAON-13NOYH101

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Date:

13 Mar 2018

Product Category:

Capacitive Touch Sensors; 8-bit PIC Microcontrollers

Notification subject:

CCB 2965.001 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using CuPdAu bond wire.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ANAC Assembly site with punched as a singulation method, using palladium coated copper wire (PdCu) bond wire and 8290 die attach material.

Post Change:

Assembled at MTAI Assembly site with sawn as a singulation method, using palladium coated copper wire with gold flash (CuPdAu) bond wire and 3280 die attach material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Microchip Technology Thailand - HQ (MTAI)
Wire material	PdCu	CuPdAu
Die attach material	8290	3280
Molding compound material	G700	G700
Lead frame material	C194	C194
Singulation method	Punched	Sawn

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying MTAI assembly site with sawn as a singulation method and using palladium coated copper wire with gold flash (CuPdAu) bond wire

Change Implementation Status:
In Progress

Estimated First Ship Date:
April 13, 2018 (date code: 1815)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	March 2018					April 2018				
	09	10	11	12	13	14	15	16	17	
Qual Report Availability			X							
Final PCN Issue Date			X							
Estimated Implementation							X			

Date										
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Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 13, 2018: Issued final notification. This PCN is qualified by similarity (QBS) to PCN # [KSRA-14SZTT575](#).

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-13NOYH101_Qual_Report.pdf](#)

[PCN_JAON-13NOYH101_Affected_CPN.pdf](#)

[PCN_JAON-13NOYH101_Affected_CPN.xlsx](#)

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